

# Product datasheet

Specifications



## redundant HSBY processor module M580 - Level 4 - Remote

Local distributor code:

408896421

BMEH584040

**EAN Code: 3606485439990**

### Main

Range of product	Modicon M580
Product or component type	Redundant processor module

### Complementary

Number of racks	1
Application specific I/O	HART SSI encoder Serial link Motion control Accurate time stamping Counter
Checks	Process control
Control channels	Programmable loops
Integrated connection type	1 Ethernet TCP/IP for service port 2 Ethernet TCP/IP for device network USB type mini B 1 Ethernet for HSBY port
Number of remote I/O station	16 - 2 rack(s) per X80 and Quantum drops
Number of distributed equipment	64
Communication module processor capacity	8 AS-Interface module 16 Ethernet communication module
Communication service	RIO scanner DIO scanner
Memory description	Expandable flash, 4 GB for data storage Integrated RAM, 10 kB for system memory Integrated RAM, 16 MB for program Integrated RAM, 2048 kB for data
Application structure	1 cyclic/periodic master task 1 periodic fast task
Cybersecurity	Achilles certified DoS prevention IPSec SNMP logging Syslog protocol support Transport layer security Audit trail Embedded firewall Firmware signature Password protection Port hardening Secure communication (HTTPS) Security log
Number of instructions per ms	30 Kinst/ms 65 % Boolean + 35 % fixed arithmetic 40 Kinst/ms 100 % Boolean

<b>Current consumption</b>	360 mA at 24 V DC
<b>MTBF reliability</b>	650000 H
<b>Marking</b>	CE

## Environment

<b>Vibration resistance</b>	3 gn
<b>Shock resistance</b>	30 gn
<b>Ambient air temperature for operation</b>	0...60 °C
<b>Ambient air temperature for storage</b>	-40...85 °C
<b>Operating altitude</b>	0...2000 m 2000...5000 m with derating factor
<b>Relative humidity</b>	5...95 % at 55 °C without condensation
<b>IP degree of protection</b>	IP20
<b>Directives</b>	2014/35/EU - low voltage directive 2014/30/EU - electromagnetic compatibility
<b>Supply</b>	Internal power supply via rack
<b>Status LED</b>	1 LED (green) processor running (RUN) 1 LED (red) processor or system fault (ERR) 1 LED (red) I/O module fault (I/O) 1 LED (green) download in progress (DL) 1 LED (red) memory card or CPU flash fault (BACKUP) 1 LED (green/red) ETH MS (Ethernet port configuration status) 1 LED (green/red) Eth NS (Ethernet network status) 1 LED (green) peer processor running (REMOTE RUN) 1 LED (green) processor ID set to A (A) 1 LED (green) processor ID set to B (B) 1 LED (green) processor acting as Primary (PRIM) 1 LED (green) processor acting as Standby (STBY) 1 LED (green) I/O values overridden by user (FORCED IO) 1 LED (green) Hot standby link status (Hsby Diag)
<b>Net weight</b>	0.849 kg

## Packing Units

<b>Unit Type of Package 1</b>	PCE
<b>Number of Units in Package 1</b>	1
<b>Package 1 Height</b>	9.100 cm
<b>Package 1 Width</b>	18.000 cm
<b>Package 1 Length</b>	25.800 cm
<b>Package 1 Weight</b>	884.000 g
<b>Unit Type of Package 2</b>	S03
<b>Number of Units in Package 2</b>	6
<b>Package 2 Height</b>	30.000 cm
<b>Package 2 Width</b>	30.000 cm
<b>Package 2 Length</b>	40.000 cm
<b>Package 2 Weight</b>	5.770 kg

## Logistical informations

<b>Country of origin</b>	FR
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# Contractual warranty

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Warranty

18 months

## Environmental Data

Schneider Electric aims to achieve Net Zero status by 2050 through supply chain partnerships, lower impact materials, and circularity via our ongoing “Use Better, Use Longer, Use Again” campaign to extend product lifetimes and recyclability.

[Environmental Data explained >](#)

[How we assess product sustainability >](#)

### Environmental footprint

Total lifecycle Carbon footprint 286

Environmental Disclosure [Product Environmental Profile](#)

## Use Better

### Materials and Substances

Packaging made with recycled cardboard Yes

Packaging without single use plastic No

[EU RoHS Directive](#) Pro-active compliance (Product out of EU RoHS legal scope)

SCIP Number 4eb70ab0-978b-4773-a441-0cc20d6144a1

REACH Regulation [REACH Declaration](#)

## Use Again

### Repack and remanufacture

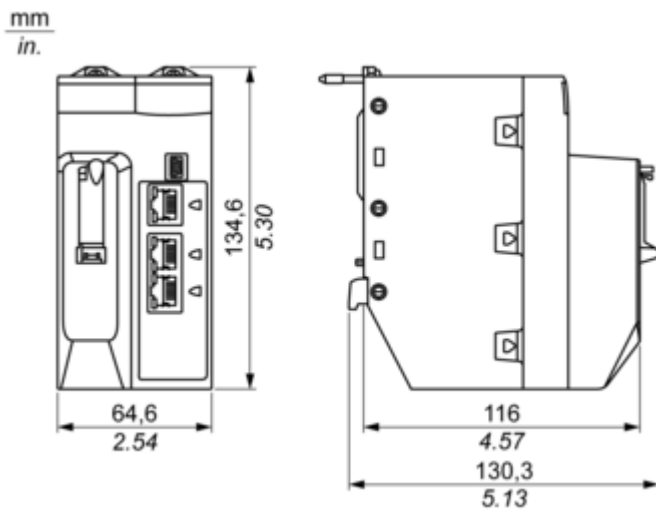
End of life manual availability [End of Life Information](#)

Take-back No

Dimensions Drawings

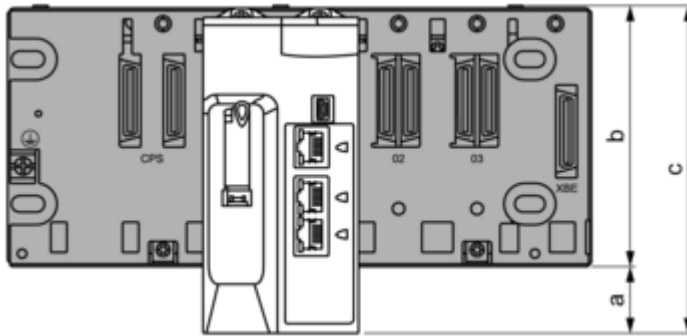
CPU Module Only

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**Modules Mounted on Racks**

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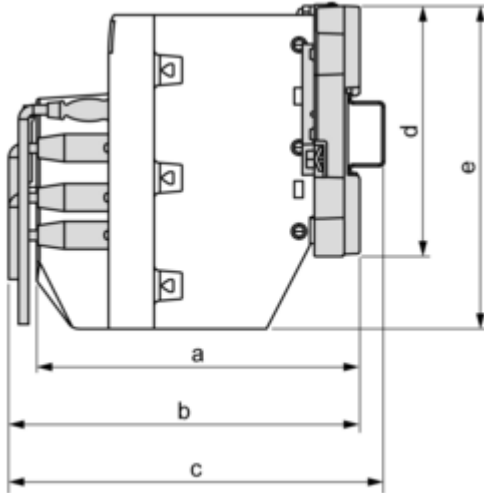
**a:** additional space below the rack to accommodate the height of the CPU. For an X Bus rack, the value is 30.9 mm (1.217 in.); for an Ethernet rack, the value is 29.49 mm (1.161 in.).

**b:** the height of the rack. For an X Bus rack, the height is 103.7 mm (4.083 in.); for an Ethernet rack, the height is 105.11 mm (4.138 in.).

**c:** the height of the main local rack, 134.6 mm (5.299 in.)

**Modules and Cables Mounted in an Enclosure**

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**a:** enclosure depth: 135 mm (5.315 in.)

**b:** wiring + module depth: > 146 mm (5.748 in.)

**c:** wiring + module + DIN rail depth: > 156 mm (6.142 in.)

**d:** rack height: for an X Bus rack 103.7 mm (4.083 in.); for an Ethernet rack, 105.11 mm (4.138 in.)

**e:** module height: 134.6 mm (5.299 in.)

Image of product / Alternate images

Alternative

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